

2017 IUS



2017 IEEE INTERNATIONAL ULTRASONICS SYMPOSIUM



WASHINGTON, D.C., USA

September 6-9, 2017



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ABSTRACT SUBMISSION NOW OPEN

Deadline for abstract submissions: April 1st, 2017.

The 2017 IEEE International Ultrasonics Symposium will be held at the **Omni Shoreham Hotel, Washington, D.C., USA, from September, 6-9, 2017.** Oral and poster presentation formats will be used. Papers are solicited for this conference describing original work in the field of Ultrasonics from the following subject classifications:

Group 1: Medical Ultrasonics

MBB Medical Beamforming and Beam Steering
MBE Biological Effects & Dosimetry
MBF Blood Flow Measurement
MCA Contrast Agents
MEL Elastography
MIM Medical Imaging
MPA Medical Photoacoustics
MSD System & Device Design
MSP Medical Signal Processing
MTC Medical Tissue Characterization
MTH Therapeutics, Hyperthermia, and Surgery

Group 2: Sensors, NDE & Industrial Applications

NAF Acoustic Microfluidics
NAI Acoustic Imaging
NAM Acoustic Microscopy
NAS Acoustic Sensors
NDE General NDE Methods
NEH Energy Harvesting
NFM Flow Measurement
NMC Material & Defect Characterization
NPA Photoacoustics
NPC Process Control
NSP Signal Processing
NTD Transducers: NDE and Industrial
NUA Underwater Acoustics
NWP Wave Propagation

Group 3: Physical Acoustics

PAT Acoustic Tweezers and Particle Manipulation
PNL Nonlinear Acoustics
PGP General Physical Acoustics
PTE High Performance and Temperature Effects
POA Opto-acoustics
PPN Phononics
PTF Thin Films
PMI Modeling and Inversion
PUM Ultrasonic Motors & Actuators
PNR Non-Reciprocal Acoustics

Group 4: Microacoustics: SAW, FBAR, MEMS

ADA Device Applications
ADD Device Design
ADM Device Modeling
AMP Materials & Propagation
AMR Microacoustic Resonators
AMS Microacoustic Sensor Devices & Apps.
ATR Tunable & Reconfigurable Devices

Group 5: Transducers & Transducer Materials

TMC Materials Fabrication and Characterization
TMO Modeling (Analytical & Numerical)
TFT Thin and Thick Piezoelectric Films
TMU Micromachined Ultrasonic Transducers
TMI Biomedical Diagnostic and Imaging Transducers
TTT Biomedical Therapeutic Transducers
THF Front-end and Integrated Electronics
TFI High Frequency Transducers
TPF Applications of Piezoelectrics & Ferroelectrics

Sponsored by the IEEE Ultrasonics, Ferroelectrics & Frequency Control Society

SUBMISSION SYSTEM ONLINE: OPEN NOW

SUBMISSION DEADLINE: APRIL 1, 2017

ACCEPTANCE NOTIFICATION: JUNE 1, 2017

<http://ewh.ieee.org/conf/ius/2017/>